



RECEIVED
JUN 12 2003
TC 1700

HF71765

[10191/1629]

REPLY UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE
GROUP ART UNIT 1765

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Franz LAERMER et al.
Serial No. : 09/720,761
Filed : March 26, 2001
For : METHOD OF PLASMA ETCHING OF SILICON
Examiner : Kin Chan Chen
Art Unit : 1765

Mail Stop AF

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop AF Commissioner for Patents, P. O. Box 1450, Alexandria, VA 22313-1450

Date: 6/5/03 Reg. No. 22,490

Signature: [Signature]
Richard L. Mayer

TRANSMITTAL

S I R:

Transmitted herewith for filing in the above-identified application is a Reply Under 37 C.F.R. § 1.116 and a certified copy of German Application 199 19 469.6.

No fee is believed to be required. However, if any fee is required, please use Deposit Account No. **11-0600**. A duplicate copy of this transmittal letter is enclosed for that purpose.

Respectfully submitted,

Dated: 6/5/03

By:

[Signature]
Richard L. Mayer
Reg. No. 22,490



26646

PATENT TRADEMARK OFFICE

KENYON & KENYON
One Broadway
New York, New York 10004
(212) 425-7200